





Integrated Device Technology, Inc.  
6024 Silver Creek Valley Road, San Jose, CA - 95138

## PRODUCT/PROCESS CHANGE NOTICE (PCN)

### ATTACHMENT I - PCN # : A0706-05

**PCN Type:** Manufacturing Site - Alternate Assembly and Bump Location

**Data Sheet Change:** None

No change in moisture sensitivity level (MSL)

**Detail Of Change:**

This notification is to advise our customers that IDT has added SPIL, Taiwan as an alternate Assembly and Bump facility for 40x40mm FPBGA 960 package.

There is no change in the moisture sensitivity level (MSL) as a result of this change.

Attachment I outlines the qualification data and affected part#s.

*Table 1*

Description	Existing	Add
Bump Location	Unitive	SPIL, Taiwan
Assembly Location	AMKOR Philippines, Korea and STATSChipPAC, Korea	SPIL, Taiwan

**Sample Availability:**

Samples are already available for customer evaluation.

Please contact your local IDT sales representative for your sample request and availability.



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#### Qualification Information and Qualification Tests Result:

**Test Vehicles:** 40x40 mm FPBGA 1413

Test Description	Test Method	Test Results (SS/ Rej)
* Temperature Cycling (-55°C to +125°C, 1000 cycles)	JESD22-A104	75/0
* HAST (85°C / 85% RH, 1000 hours)	JESD22-A110	45/0
High Temperature Stabilization Bake (150 °C, 1000 hours)	JESD22-A103	45/0
Moisture Sensitivity Classification, L4	J-STD-020	90/0

**Notes:** \* Test requires moisture pre-conditioning sequence per JESD22-A113.

#### Affected Part #s

IDT89TTM553BL